

### General Description

This Power MOSFET is produced using Cmos's advanced planar stripe DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switched mode power supplies, active power factor correction based on half bridge topology.

### Features

- 16A, 250V,  $R_{DS(ON)} < 250m\Omega$  @  $V_{GS} = 10V$
- 100% avalanche tested
- Simple Drive Requirements
- RoHS Compliant

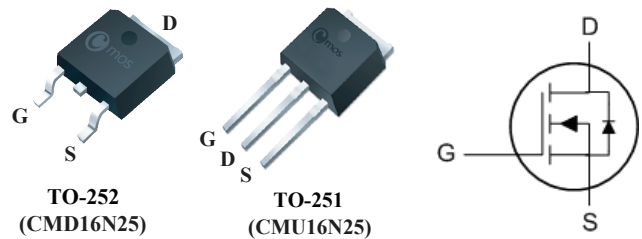
### Product Summary

BVDSS	RDSON	ID
250V	250mΩ	16A

### Applications

- PWM Motor Controls
- LED TV
- DC-DC Converters

### TO-252/251 Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	250	V
$V_{GS}$	Gate-Source Voltage	$\pm 30$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current	16	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current	7.2	A
$I_{DM}$	Pulsed Drain Current	64	A
EAS	Single Pulse Avalanche Energy	350	mJ
$I_{AR}$	Avalanche Current	27	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	35	W
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

### Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	62.5	$^\circ C/W$
$R_{\theta JC}$	Thermal Resistance Junction -Case	---	3.57	$^\circ C/W$

### Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ , unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V$ , $I_D=250\mu A$ , $T_J=25^{\circ}\text{C}$	250	---	---	V
$BV_{DSS}/\Delta T_J$	Zero Gate Voltage Drain Current	$I_D=250\mu A$ , $V_{GS}=0V$	---	0.31	---	V/°C
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10V$ , $I_D=8A$	---	210	250	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$ , $I_D=250\mu A$	2	---	4	V
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=250V$ , $V_{GS}=0V$	---	---	1	μA
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 30V$	---	---	±100	nA
$g_{fs}$	Forward Transconductance	$V_{DS}=15V$ , $I_D=8A$	---	11	---	S
$Q_g$	Total Gate Charge	$V_{DS}=200V$ , $V_{GS}=10V$ , $I_D=16A$	---	23	---	nC
$Q_{gs}$	Gate-Source Charge		---	7	---	
$Q_{gd}$	Gate-Drain Charge		---	6.5	---	
$T_{d(on)}$	Turn-On Delay Time	$V_{DS}=125V$ , $V_{GS}=10V$ , $R_G=25\Omega$ $I_D=16A$	---	18	---	ns
$T_r$	Rise Time		---	30	---	
$T_{d(off)}$	Turn-Off Delay Time		---	133	---	
$T_f$	Fall Time		---	40	---	
$C_{iss}$	Input Capacitance	$V_{DS}=25V$ , $V_{GS}=0V$ , $f=1\text{MHz}$	---	1200	---	pF
$C_{oss}$	Output Capacitance		---	150	---	
$C_{rss}$	Reverse Transfer Capacitance		---	55	---	

### Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	16	A
$I_{SM}$	Pulsed Source Current		---	---	64	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V$ , $I_F=15A$ , $T_J=25^{\circ}\text{C}$	---	---	1.4	V
$t_{rr}$	Reverse Recovery Time	$I_F=16A$ , $V_{GS}=0V$	---	208	---	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt=100A/\mu s$	---	1.63	---	nC

Note :

1.Starting  $T_J=25^{\circ}\text{C}$  ,  $L=1\text{mH}$  ,  $V_{DD}=150V$  ,  $I_{AS}=27A$ .

This product has been designed and qualified for the consumer market.

Cmos assumes no liability for customers' product design or applications.

Cmos reserves the right to improve product design ,functions and reliability without notice.